

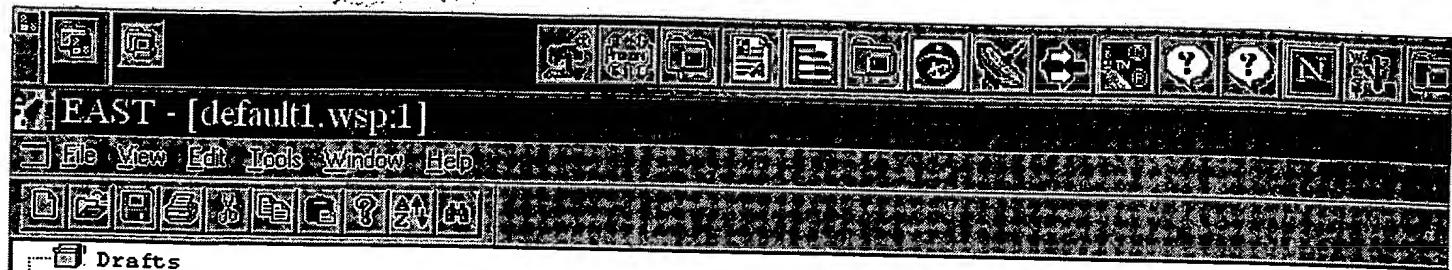
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 - ISNR:
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 - BRS:
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- Active
 - L1: (4230) ic same thermal
 - L2: (2) adaptive same 1
 - L3: (265) ic and (thermal adj4 manage\$5)
 - L4: (27) overclock\$3
 - L6: (0) 1 and 4
 - L7: (0) 3 and 4
 - L5: (107) 1 and 3
 - L8: (8100) bios
 - L9: (6) 4 and 8
 - L10: (2) 3 and 8
 - L11: (1) "5825972".PN.
 - L12: (1) "5460009".PN.
 - L13: (1) "5457766".PN.
 - L14: (1) "5197858".PN.
 - L15: (1) "5099181".PN.
 - L16: (1) "4168456".PN.
 - L17: (7) overclock\$3 and (thermal adj4 manage\$5)
- Failed
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4	<input type="checkbox"/>	<input type="checkbox"/> US 6459334 B2	20021001	193	Amplifier measurement and modeling processes for use in generating predistortion parameters	3



Category	Count
L1: (765) power same thermal adj management	765
L2: (35) bios and 1	35
L3: (7) bios same 1	7
Failed	0
Saved	0
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